

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) ~~A performance adjusting device for~~ An inertia sensor includes:

a suspension structure, one side of which the suspension structure is being connected firmly to a supporting piece, such that and another side of the suspension structure is shown as being in a suspending state, the suspension structure further comprising an arm and a platform, one side of the arm being arranged firmly at the supporting piece, another side of the arm being in the suspending state, the platform being arranged at the one side of the arm and being in the suspending state, the platform being configured by horizontally extending a specific length to form two top sides of the platform and taking the arm at a center of the two top sides of the platform; and

a micro-electroplating structure, which is being formed at another side of the suspension structure by micro-electroplating process and is shown as being in the suspending state with a specific altitude, the micro-electroplating structure being respectively arranged at the two top sides of the platform;

a reinforcing structure, the reinforcing structure including an inside reinforcing structure and an outside reinforcing structure, the inside reinforcing structure being arranged at the two top sides of the arm and being extended along the inside of the platform and being connected to the micro-electroplating structure, the outside reinforcing structure being arranged at the outside of the platform and being not connected to the micro-electroplating structure.

2-3. (Cancelled)

4. (Currently Amended) The ~~performance-adjusting device for inertia~~ sensor according to claim 1, wherein the suspension structure is a vibratory structure arranged on the inertia sensor.

5. (Currently Amended) The ~~performance-adjusting device for inertia~~ sensor according to claim 1, wherein the suspension structure is processed by surface micromachining, or by bulk micromachining technique incorporating with thin film technique.

6. (Currently Amended) The ~~performance-adjusting device for inertia~~ sensor according to claim 1, wherein the suspension structure includes a supporting structure, a signal-connecting path, and a signal-isolation layer.

7. (Currently Amended) The ~~performance-adjusting device for inertia~~ sensor according to claim 1, wherein the micro-electroplating process includes following the steps of:

(a) ~~Preparing~~ preparing a suspension-based structure;

(b) ~~Electroplating~~ electroplating a plating seed layer upon the suspension-based structure;

(c) ~~Setting~~setting up a thick film photoresist of isolation upon the plating seed layer;

(d) ~~Forming~~forming a metallic plating layer having a specific thickness between each thick film photoresist;

(e) ~~Removing~~removing the thick film photoresist;

(f) ~~Removing~~removing the plating seed layer; and

(g) ~~Removing~~removing the a sacrificial layer, and forming a suspension structure constructed by both a suspension structure layer and the metallic plating layer.